

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- ●Ideal for high-frequency switching and synchronous rectification

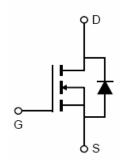
General Features

- V_{DS} =85V, I_D =320A $R_{DS(ON)}$ =1.6m Ω , typical @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

TO-247





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP020N85T	NCEP020N85T	TO-247	-	-	-

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	85	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	320	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	245	Α
Pulsed Drain Current	I _{DM}	1280	Α
Maximum Power Dissipation	P _D	365	W
Derating factor		2.43	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	2850	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	R _{0JC}	0.41	°C/W



Electrical Characteristics (T_C=25°C unless otherwise noted)

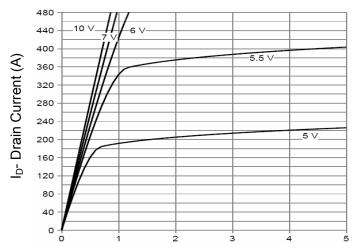
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85		=	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =160A	-	1.6	2.0	mΩ
Gate resistance	R _G		2	-	5	Ω
Forward Transconductance	g FS	V _{DS} =5V,I _D =160A		210	-	S
Dynamic Characteristics (Note4)	•		•			
Input Capacitance	C _{Iss}		-	15800	=	PF
Output Capacitance	C _{oss}	V _{DS} =40V,V _{GS} =0V, F=1.0MHz	-	2450	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	111	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	43	-	nS
Turn-on Rise Time	t _r	V_{DD} =40V, I_{D} =160A	-	39	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	108	-	nS
Turn-Off Fall Time	t _f		-	40	-	nS
Total Gate Charge	Qg	\/ -40\/ L -400A	-	245	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =40V, I_{D} =160A, V_{GS} =10V	-	66		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	65		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =160A	-		1.2	V
Diode Forward Current	Is		-	-	320	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 160A	-	109	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	315	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =40 V,V $_{\text{G}}$ =10 V,L=0.5 mH,Rg=25 Ω

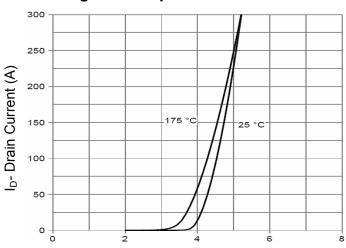


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)





Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

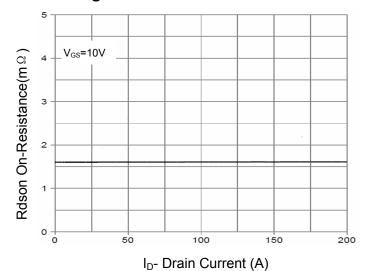
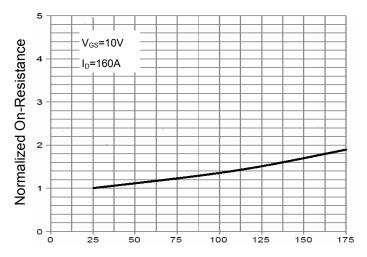
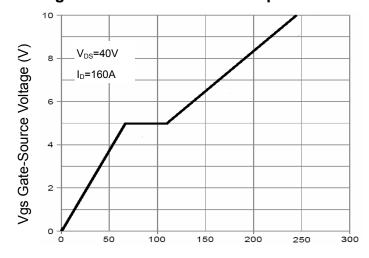


Figure 3 Rdson- Drain Current

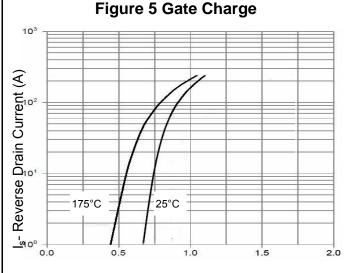


T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



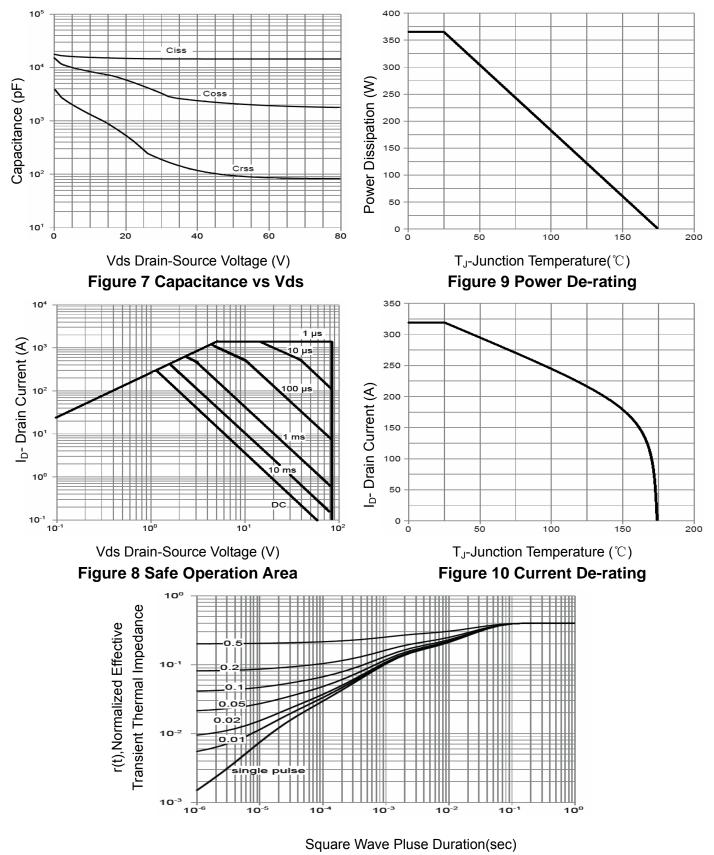
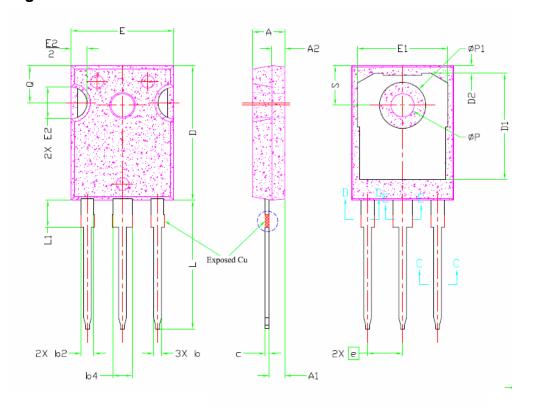
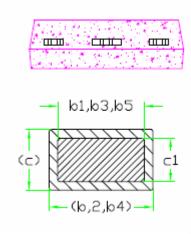


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-247 Package Information





ova apor				
SYMBOL	MIN.	NOM.	MAX.	NOTES
Α	4.83	5.02	5.21	
A1	2,29	2,41	2,55	
A2	1,50	2,00	2.49	
b	1.12	1.20	1.33	
b1	1.12	1.20	1.28	
b2	1.91	2.00	2.39	6
b3	1.91	2.00	2.34	
b4	2,87	3,00	3,22	6,8
b5	2.87	3,00	3,18	
С	0.55	0.60	0.69	6
c1	0.55	0.60	0.65	
D	20.80	20.95	21.10	4
D1	16.25	16.55	17.65	5
D2	0.51	1,19	1,35	
E	15,75	15,94	16,13	4
E1	13.46	14.02	14.16	5
E2	4.32	4.91	5.49	3
е	5.44BSC			
L	19,81	20,07	20.32	
L1	4.10	4,19	4.40	6
ØP	3,56	3.61	3.65	7
ØP1	7.19REF.			
α	5.39	5.79	6.20	
S	6.04	6.17	6.30	



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